

**DESCRIPTION**

The AM045NS10LD is available in TO-252 Packages.

BVDSS	RDSON	ID
100V	45mΩ@10V	15A

APPLICATION

- Power switching application
- Battery management
- Uninterruptible power supply

ORDERING INFORMATION

Package Type	Part Number	
TO-252	D	AM045NS10LD
Note	SPQ:2,500pcs/Reel	
AiT provides all RoHS products		

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current (T _c =25°C)	I _D	15	A
Continuous Drain Current (T _c =100°C)	I _D	10	A
Pulsed Drain Current	I _{DM}	60	A
Single Pulse Avalanche Energy ¹	E _{AS}	20	mJ
Power Dissipation (T _c =25°C)	P _D	35	W
Power Dissipation (T _c =100°C)	P _D	14	W
Thermal Resistance Junction-to-Case	R _{θJC}	3.57	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

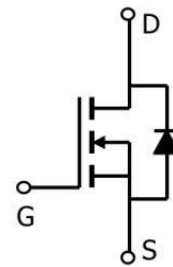
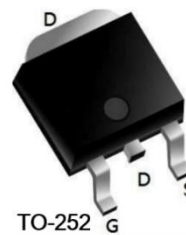
(1) Pulse width limited by maximum junction temperature

(2) L=20mH, V_{DS}=50V, Start T_A=25°C

(3) I_{SD} = 4.8A, di/dt ≤ 100A/μs, V_{DD} ≤ BV_{DSS}, Start T_A=25°C

FEATURE

- Fast Switching
- Low Gate Charge and R_{DS(on)}
- R_{DS(ON)typ.} = 45mΩ @ V_{GS}=10V
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

PIN DESCRIPTION

Pin#	Symbol	Function
1	G	Gate
2	D	Drain
3	S	Source

**ELECTRICAL CHARACTERISTICS**T_A = 25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V , ID=250uA	100	-	-	V
Drain Cut-Off Current	I _{DSS}	VDS=80V , VGS=0V , TJ=25°C	-	-	1	μA
Gate Leakage Current	I _{GSS}	VGS=±20V , VDS=0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	VGS=VDS , ID=250uA	1.5	1.9	2.5	V
Drain-Source ON Resistance	R _{DS(ON)}	VGS=10V , ID=10A	-	45	56	mΩ
		VGS=4.5V , ID=8A	-	60	-	
Gate Resistance	R _G	VDS=50V , VGS=0V , f=1MHz	-	6.2	-	Ω
Dynamic Characteristics						
Input Capacitance	R _g	VDS=50V , GS=0V , f=1MHz	-	392	-	pF
Output Capacitance	C _{iss}		-	94	-	
Reverse Transfer Capacitance	C _{oss}		-	7	-	
Total Gate Charge	C _{rss}	VDS=50V , GS=10V , ID=10A	-	6	-	nC
Gate-Source Charge	Q _g		-	1.5	-	
Gate-Drain Charge	Q _{gs}		-	2	-	
Gate Plateau Voltage	Q _{gd}		-	4	-	V
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	VDD=50V, VGS=10V , RG=3Ω , ID=10A	-	4.5	-	nS
Rise Time	t _r		-	5	-	
Turn-Off Delay Time	t _{d(off)}		-	13	-	
Fall Time	t _f		-	5	-	
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V _{SD}	IS=1A , VGS=0V , TJ=25°C	-	-	1.2	V
Maximum Body-Diode Continuous Current	I _s		-	-	15	A
Reverse Recovery Time	T _{rr}	IS=10A , i/dt=100A/us , TJ=25°C	-	2	-	nS
Reverse Recovery Charge	Q _{rr}		-	35	-	nC

(4) : Pulse width tp≤300μs, δ≤2%



TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Typical Output Characteristics

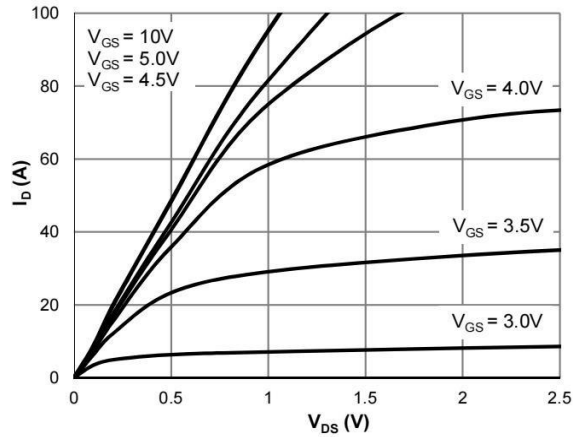


Fig 2. Transfer Characteristics

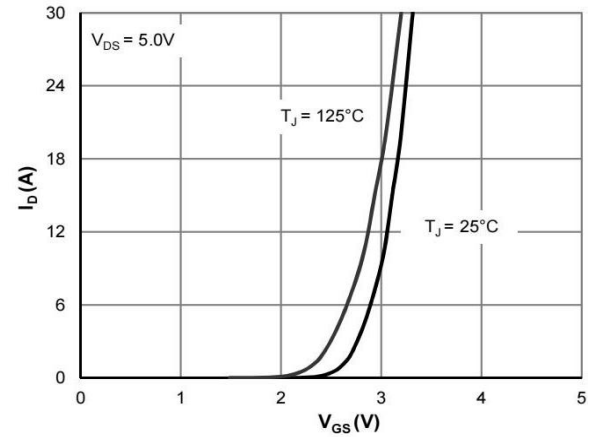


Fig 3. On-Resistance vs. Drain Current

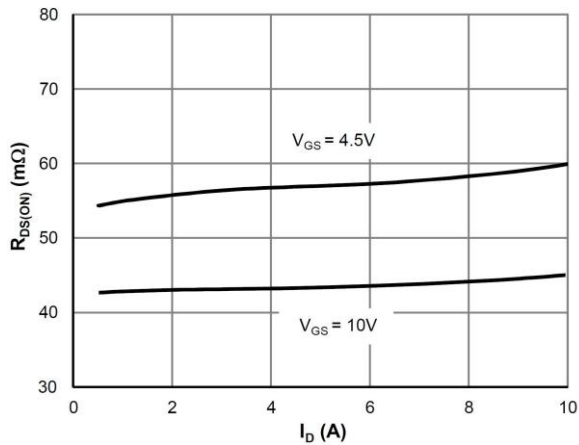


Fig 4. On-Resistance vs. Junction Temperature

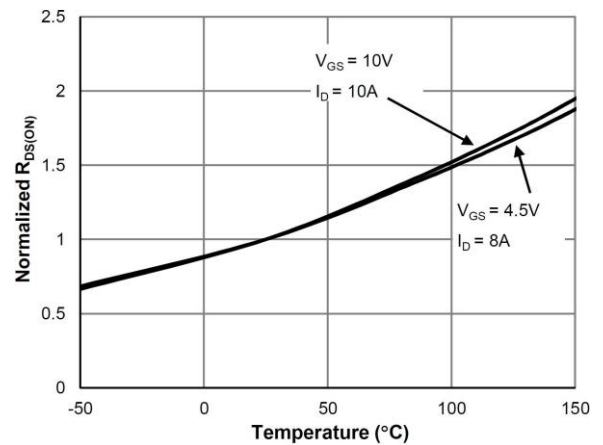


Fig 5. Body-Diode Characteristics

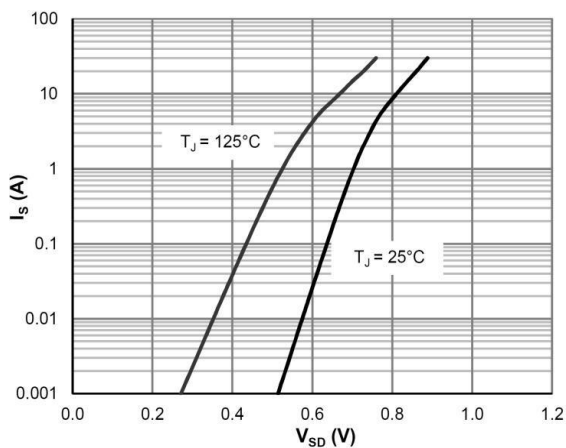


Fig 6. Capacitance Characteristics

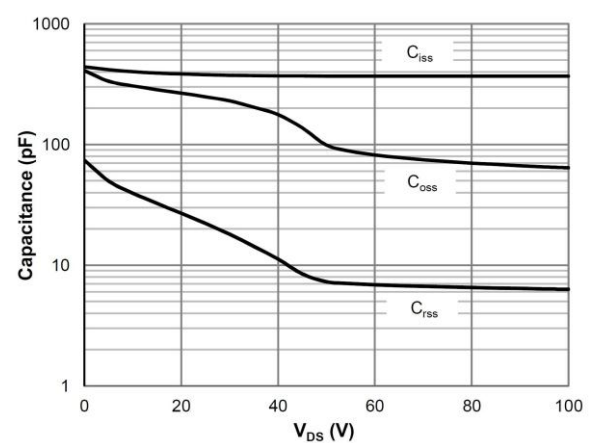




Fig 8. Current De-rating

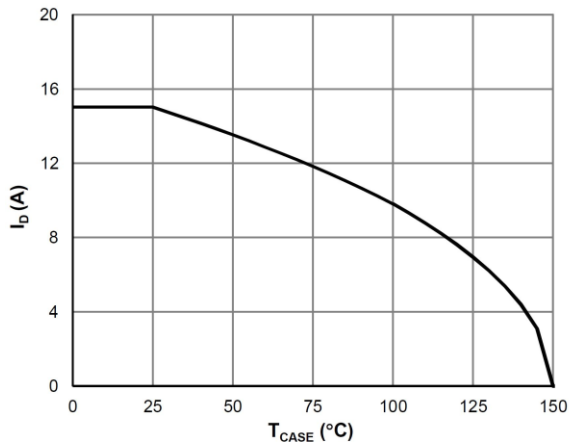


Fig 9. Power De-rating

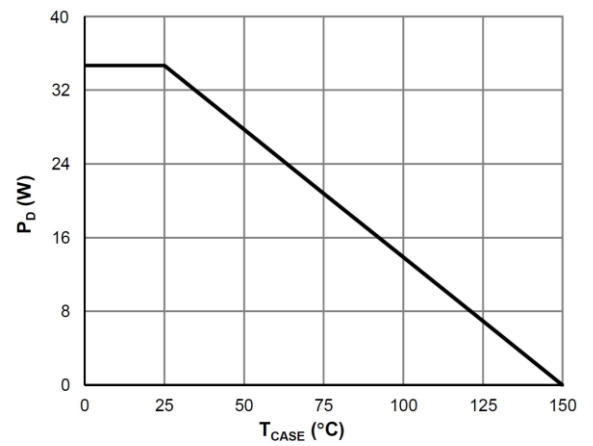


Fig 10. Maximum Safe Operating Area

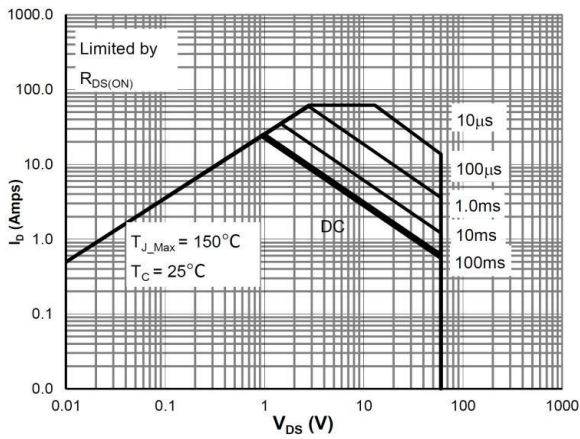


Fig 11. Single Pulse Power Rating, Junction-to-Case

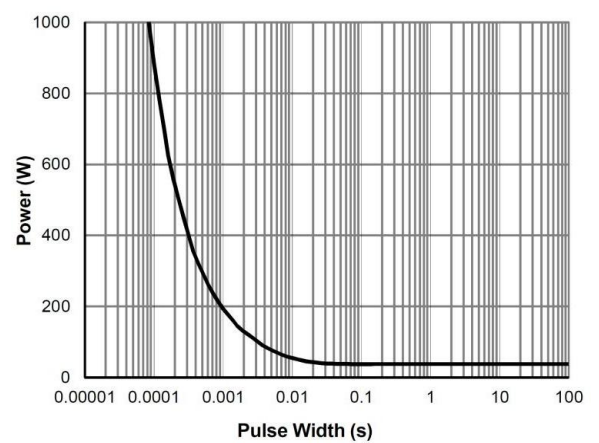
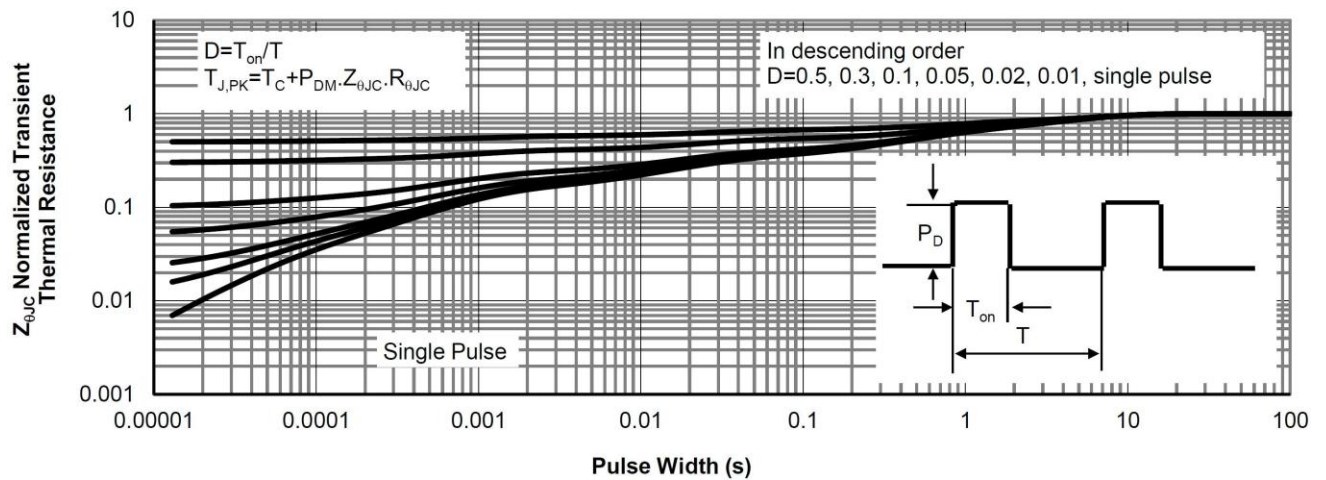


Fig 11. Normalized Maximum Transient Thermal Impedance





Test Circuit & Waveform

Fig 12. Gate Charge Test Circuit & Waveform

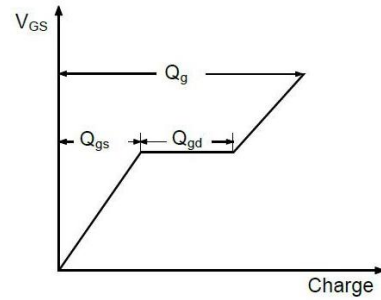
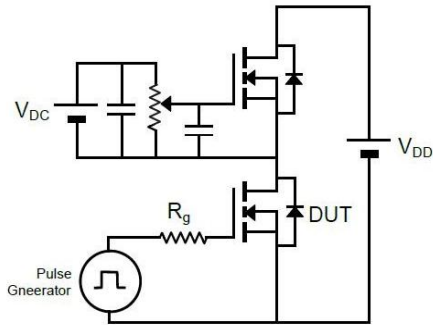


Fig 13. Resistive Switching Test Circuit & Waveform

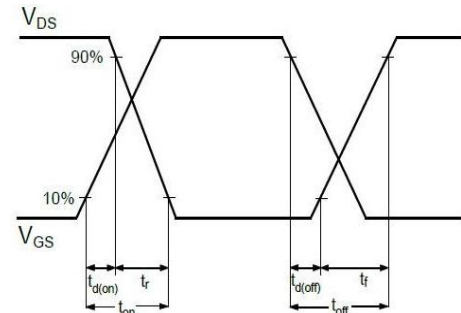
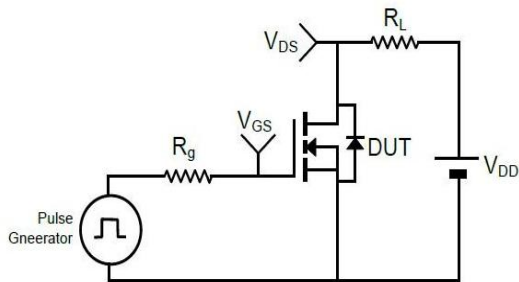


Fig 14. Un-clamped Inductive Load Switching Test Circuit & Waveform

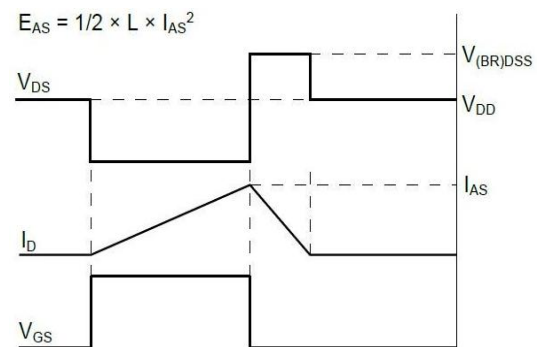
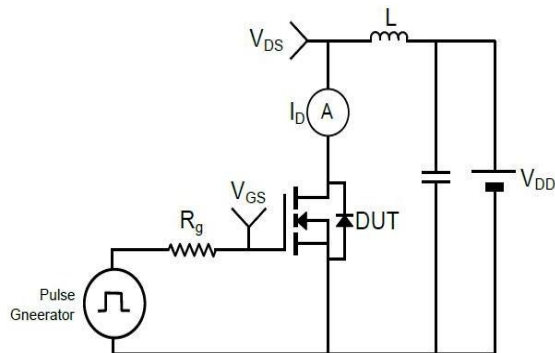
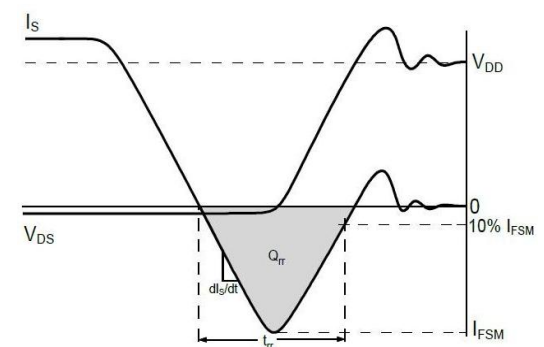
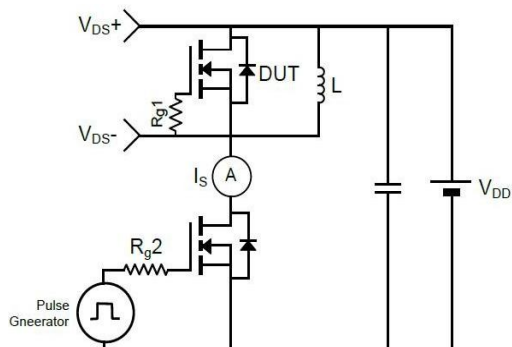


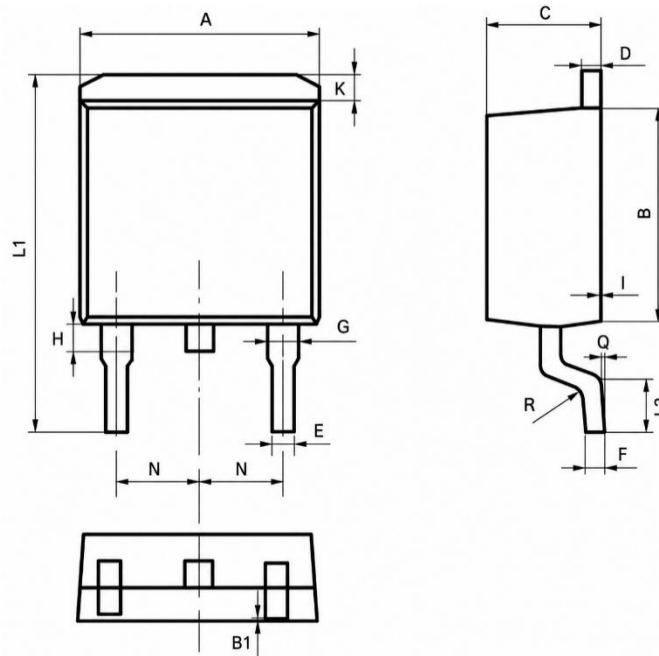
Fig 15. Drain-Source Body Diode Reverse Recovery Test Circuit & Waveforms





PACKAGE INFORMATION

Dimension in TO-252 (Unit: mm)



Symbol	Min.	Max.
A	9.800	10.40
B	8.900	9.500
B1	0	0.100
C	4.400	4.800
D	1.160	1.370
E	0.700	0.950
F	0.300	0.600
G	1.070	1.470
H	1.300	1.800
K	0.950	1.370
L1	14.50	16.50
L2	1.600	2.300
I	0	0.2
Q	0°	8°
R	0.4	
N	2.390	2.690

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